(0.80 mm) .0315"

## **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?HTEC8

Insulator Material:
Black LCP
Contact Material:
Copper Alloy
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Operating Temp Range:
Testing Now!
Current Rating:
3.0 A per pin
(2 pins powered)
Voltage Rating:
Testing Now!
RoHS Compliant:

## **PROCESSING**

Lead-Free Solderable: Yes

SMT Lead Coplanarity: (0.10 mm) .004" max (20-60) (0.13 mm) .005" max (80-100)\* \*(.004" stencil solution may be available; contact IPG@samtec.com)

## RECOGNITIONS

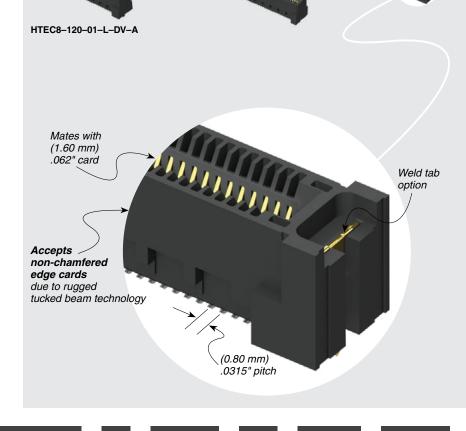
For complete scope of recognitions see www.samtec.com/quality



## Mates with:

(1.60 mm) .062" thick card





HTEC8-160-01-S-DV-A



POSITIONS

**PER ROW** 

Leave blank for no Alignment Pin Gold on contact, Matte Tin on tail

-S
= 30 \mu" (0.76 \mum) Gold on contact, Matte Tin on tail

POSITIONS PER ROW

20

30

**PLATING** 

**OPTION** 

No. of Positions x (0.80) .0315 + (7.80) .307

01

Leave
blank for no
Alignment
Pin

-A

-WT
= Weld Tab
(-A option
required)

-K

OPTION

В

(23.20) .913

> (1.48) .058

Α

(25.40)

(17.40) (15.20) .685 5.98

(0.64) .025 → | ← -WT OPTION

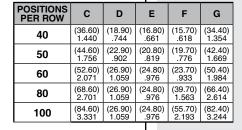
HTEC8-130-01-S-DV-A-WT

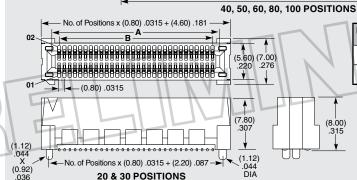
= (7.00 mm) .276" DIA Polyimide Pick & Place Pad

**OTHER** 

**OPTION** 

—TR = Tape & Reel (–20 thru 60 positions only) (Leave blank for tray)





Due to technical progress, all designs, specifications and components are subject to change without notice

Some sizes, styles and options are non-standard, non-returnable.

Notes:

WWW.SAMTEC.COM